

**Amendments to the Specification:**

Please replace the abstract with the following amended abstract:

**Abstract**

Apparatus and methods for testing conductive bumps or target test points on integrated circuits comprising a multiplicity of probes extending through a support substrate. At least one of the multiplicity of probe locations including a second electrically isolated probe such that the test point is in contact with two probes. One of the two probes providing a voltage to the test point and the second probe sensing the voltage so as to provide a Kelvin connection.